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STM32F469xx

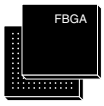
ARM®Cortex®-M4 32b MCU+FPU, 225DMIPS, up to 2MB Flash/384+4KB RAM, USB OTG HS/FS, Ethernet, FMC, dual Quad-SPI, Graphical accelerator, Camera IF, LCD-TFT & MIPI DSI

Datasheet - production data

Features

- Core: ARM® 32-bit Cortex®-M4 CPU with FPU, Adaptive real-time accelerator (ART Accelerator™) allowing 0-wait state execution from Flash memory, frequency up to 180 MHz, MPU, 225 DMIPS/1.25 DMIPS/MHz (Dhrystone 2.1), and DSP instructions
- Memories
  - Up to 2 MB of Flash memory organized into two banks allowing read-while-write
  - Up to 384+4 KB of SRAM including 64 KB of CCM (core coupled memory) data RAM
  - Flexible external memory controller with up to 32-bit data bus: SRAM, PSRAM, SDRAM/LPSDR, SDRAM, Flash NOR/NAND memories
  - Dual-flash mode Quad-SPI interface
- Graphics:
  - Chrom-ART Accelerator™ (DMA2D), graphical hardware accelerator enabling enhanced graphical user interface with minimum CPU load
  - LCD parallel interface, 8080/6800 modes
  - LCD TFT controller supporting up to XGA resolution
  - MIPI® DSI host controller supporting up to 720p 30Hz resolution
- Clock, reset and supply management
  - 1.7 V to 3.6 V application supply and I/Os
  - POR, PDR, PVD and BOR
  - 4-to-26 MHz crystal oscillator
  - Internal 16 MHz factory-trimmed RC (1% accuracy)
  - 32 kHz oscillator for RTC with calibration
  - Internal 32 kHz RC with calibration
- Low power
  - Sleep, Stop and Standby modes
  - V_{BAT} supply for RTC, 20×32 bit backup registers + optional 4 KB backup SRAM
- 3×12-bit, 2.4 MSPS ADC: up to 24 channels and 7.2 MSPS in triple interleaved mode
- 2×12-bit D/A converters
- General-purpose DMA: 16-stream DMA controller with FIFOs and burst support
- Up to 17 timers: up to twelve 16-bit and two 32-bit timers up to 180 MHz, each with up to 4 IC/OC/PWM or pulse counter and quadrature (incremental) encoder input. 2x watchdogs and SysTick timer

LQFP100 (14 × 14 mm)
LQFP144 (20 × 20 mm)
LQFP176 (24 × 24 mm)
LQFP208 (28 × 28 mm)



UFBGA169 (7 × 7 mm)
UFBGA176 (10 x 10 mm)
TFBGA216 (13 x 13 mm)

WLCSP168

- Debug mode
  - SWD & JTAG interfaces
  - Cortex®-M4 Trace Macrocell™
- Up to 161 I/O ports with interrupt capability
  - Up to 157 fast I/Os up to 90 MHz
  - Up to 159 5 V-tolerant I/Os
- Up to 21 communication interfaces
  - Up to 3 × I^2C interfaces (SMBus/PMBus)
  - Up to 4 USARTs and 4 UARTs (11.25 Mbit/s, ISO7816 interface, LIN, IrDA, modem control)
  - Up to 6 SPIs (45 Mbits/s), 2 with muxed full-duplex I^2S for audio class accuracy via internal audio PLL or external clock
  - 1 x SAI (serial audio interface)
  - 2 × CAN (2.0B Active)
  - SDIO interface
- Advanced connectivity
  - USB 2.0 full-speed device/host/OTG controller with on-chip PHY
  - USB 2.0 high-speed/full-speed device/host/OTG controller with dedicated DMA, on-chip full-speed PHY and ULPI
  - Dedicated USB power rail enabling on-chip PHYs operation throughout the entire MCU power supply range
  - 10/100 Ethernet MAC with dedicated DMA: supports IEEE 1588v2 hardware, MII/RMII
- 8- to 14-bit parallel camera interface up to 54 Mbytes/s
- True random number generator
- CRC calculation unit
- RTC: subsecond accuracy, hardware calendar
- 96-bit unique ID

Table 1. Device summary

Reference	Part numbers
STM32F469xx	STM32F469AE, STM32F469AG, STM32F469AI STM32F469BE, STM32F469BG, STM32F469BI STM32F469IE, STM32F469IG, STM32F469II STM32F469NE, STM32F469NG, STM32F469NI STM32F469VE, STM32469VG, STM32469VI STM32F469ZE, STM32469ZG, STM32469ZI

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1 Description

The STM32F469xx devices are based on the high-performance ARM® Cortex®-M4 32-bit RISC core operating at a frequency of up to 180 MHz. The Cortex®-M4 core features a Floating point unit (FPU) single precision which supports all ARM® single-precision data-processing instructions and data types. It also implements a full set of DSP instructions and a memory protection unit (MPU) which enhances application security.

The STM32F469xx devices incorporate high-speed embedded memories (Flash memory up to 2 Mbytes, up to 384 Kbytes of SRAM), up to 4 Kbytes of backup SRAM, and an extensive range of enhanced I/Os and peripherals connected to two APB buses, two AHB buses and a 32-bit multi-AHB bus matrix.

All devices offer three 12-bit ADCs, two DACs, a low-power RTC, twelve general-purpose 16-bit timers including two PWM timers for motor control, two general-purpose 32-bit timers, and a true random number generator (RNG). They also feature standard and advanced communication interfaces:

- Up to three I^2Cs
- Six SPIs, two I^2Ss full duplex. To achieve audio class accuracy, the I^2S peripherals can be clocked via a dedicated internal audio PLL or via an external clock to allow synchronization.
- Four USARTs plus four UARTs
- An USB OTG full-speed and a USB OTG high-speed with full-speed capability (with the ULPI),
- Two CANs
- One SAI serial audio interface
- An SDMMC host interface
- Ethernet and camera interface
- LCD-TFT display controller
- Chrom-ART Accelerator™
- DSI Host.

Advanced peripherals include an SDMMC interface, a flexible memory control (FMC) interface, a Quad-SPI Flash memory, and camera interface for CMOS sensors. Refer to *Table 2* for the list of peripherals available on each part number.

The STM32F469xx devices operate in the –40 to +105 °C temperature range from a 1.7 to 3.6 V power supply. A dedicated supply input for USB (OTG_FS and OTG_HS) only in full speed mode, is available on all packages.

The supply voltage can drop to 1.7 V (refer to *Section 2.19.2*). A comprehensive set of power-saving mode allows the design of low-power applications.

The STM32F469xx devices are offered in eight packages, ranging from 100 to 216 pins. The set of included peripherals changes with the device chosen, according to *Table 2*.

These features make the STM32F469xx microcontrollers suitable for a wide range of applications:

- Motor drive and application control
- Medical equipment
- Industrial applications: PLC, inverters, circuit breakers
- Printers, and scanners
- Alarm systems, video intercom, and HVAC
- Home audio appliances

Figure 5 shows the general block diagram of the device family.

Table 2. STM32F469xx features and peripheral counts

Peripherals		STM32F469Vx	STM32F469Zx	STM32F469Ax	STM32F469Ix	STM32F469Bx	STM32F469Nx
Flash memory in Kbytes		512 1024 2048	512 1024 2048	512 1024 2048	512 1024 2048	512 1024 2048	512 1024 2048
SRAM in Kbytes	System	384 (160+32+128+64)					
	Backup	4					
FMC memory controller		Yes					
Quad-SPI		Yes					
Ethernet		No			Yes		
Timers	General-purpose	10					
	Advanced-control	2					
	Basic	2					
Random number generator		Yes					
Communication interfaces	SPI / I^2S	4/2(full duplex)(1)		6/2(full duplex)(1)			
	I^2C	3					
	USART/UART	4/3		4/4			
	USB OTG FS	Yes					
	USB OTG HS	Yes					
	CAN	2					
	SAI	1					
	SDIO	Yes					
Camera interface		Yes					

Table 2. STM32F469xx features and peripheral counts (continued)

Peripherals	STM32F469Vx	STM32F469Zx	STM32F469Ax	STM32F469Ix	STM32F469Bx	STM32F469Nx
MIPI-DSI Host	Yes					
LCD-TFT	Yes					
Chrom-ART Accelerator™ (DMA2D)	Yes					
GPIOs	71	106	114	131	161	161
12-bit ADC Number of channels	3					
	14	20	24	16	24	24
12-bit DAC Number of channels	Yes 2					
Maximum CPU frequency	180 MHz					
Operating voltage	1.7 to 3.6V(2)					
Operating temperatures	Ambient operating temperature: −40 to 85 °C / −40 to 105 °C Junction temperature: −40 to 105 °C / −40 to 125 °C					
Package	LQFP100	LQPF144	UFBGA169 WLCSP168	LQFP176 UFBGA176	LQFP208	TFBGA216

1. The SPI2 and SPI3 interfaces give the flexibility to work in an exclusive way in either the SPI mode or the I2S audio mode.
2. VDD/VDDA minimum value of 1.7 V is obtained when the internal reset is OFF (refer to *Section 2.19.2*).

1.1 Compatibility throughout the family

STM32F469xx devices are not compatible with other STM32F4xx devices.

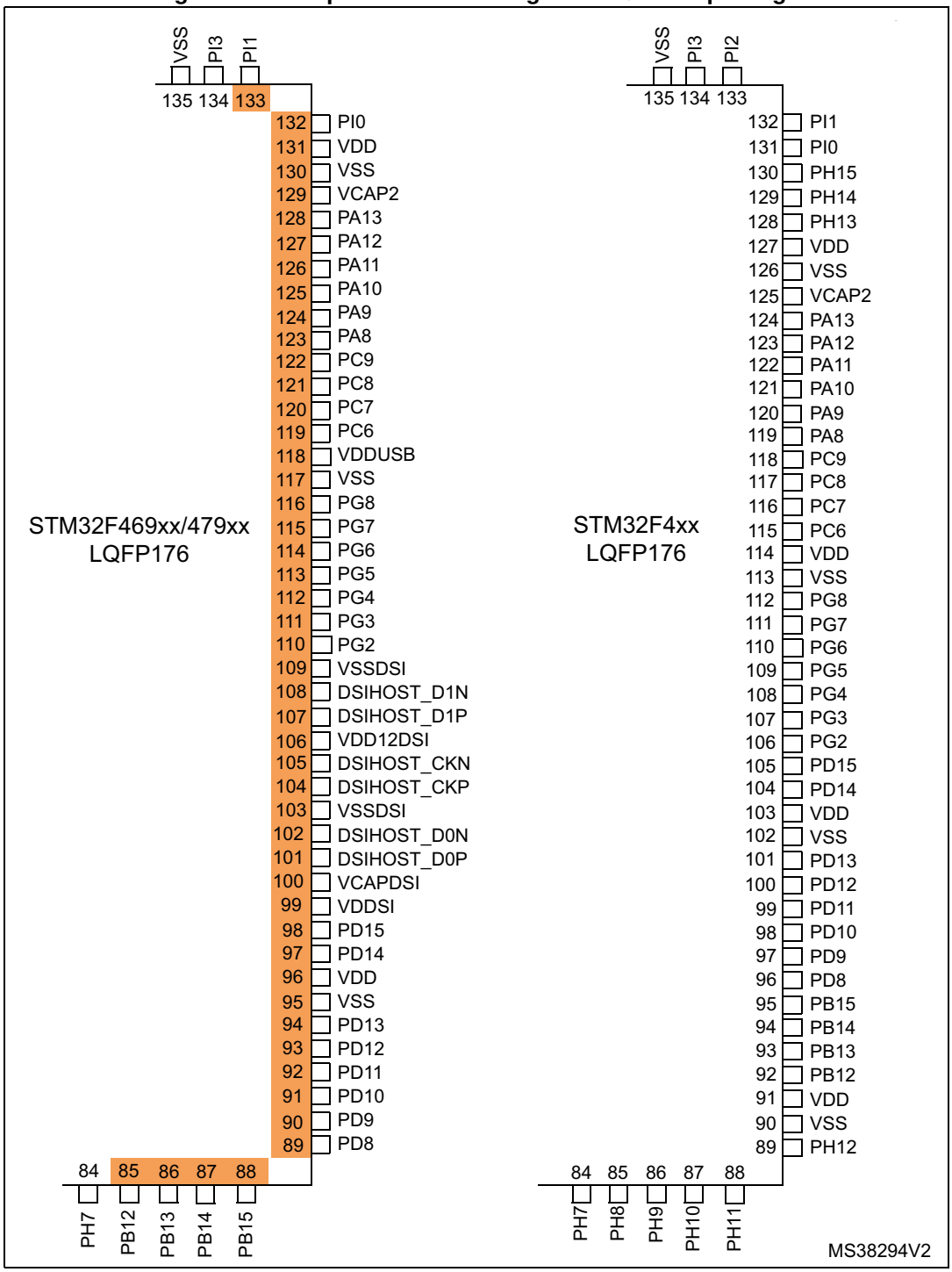
Figure 1 and *Figure 2* show incompatible board designs, respectively, for LQFP176 and LQFP208 packages (highlighted pins).

The UFBGA176 and TFBGA216 ballouts are compatible with other STM32F4xx devices, only few IO port pins are substituted, as shown in *Figure 3* and *Figure 4*.

The LQFP100, LQFP144 and UFBGA169 packages are incompatible with other STM32F4xx devices.

1.1.1 LQFP176 package

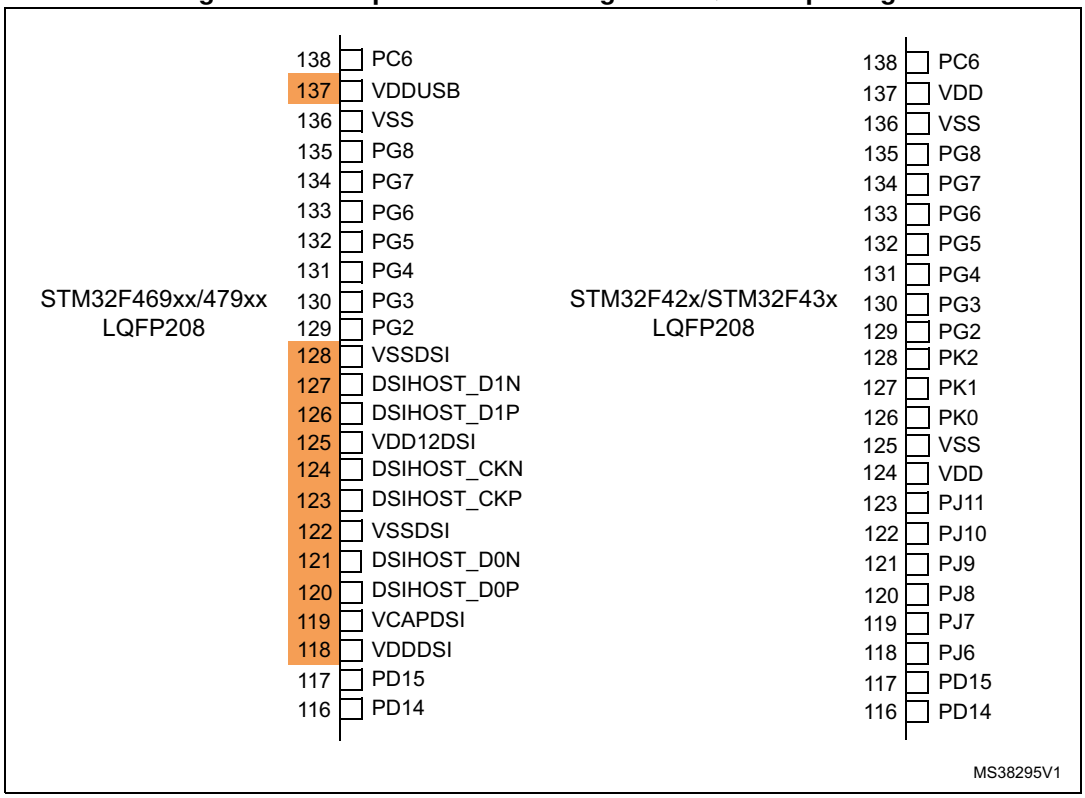
Figure 1. Incompatible board design for LQFP176 package



1. Pins from 85 to 133 are not compatible.

1.1.2 LQFP208 package

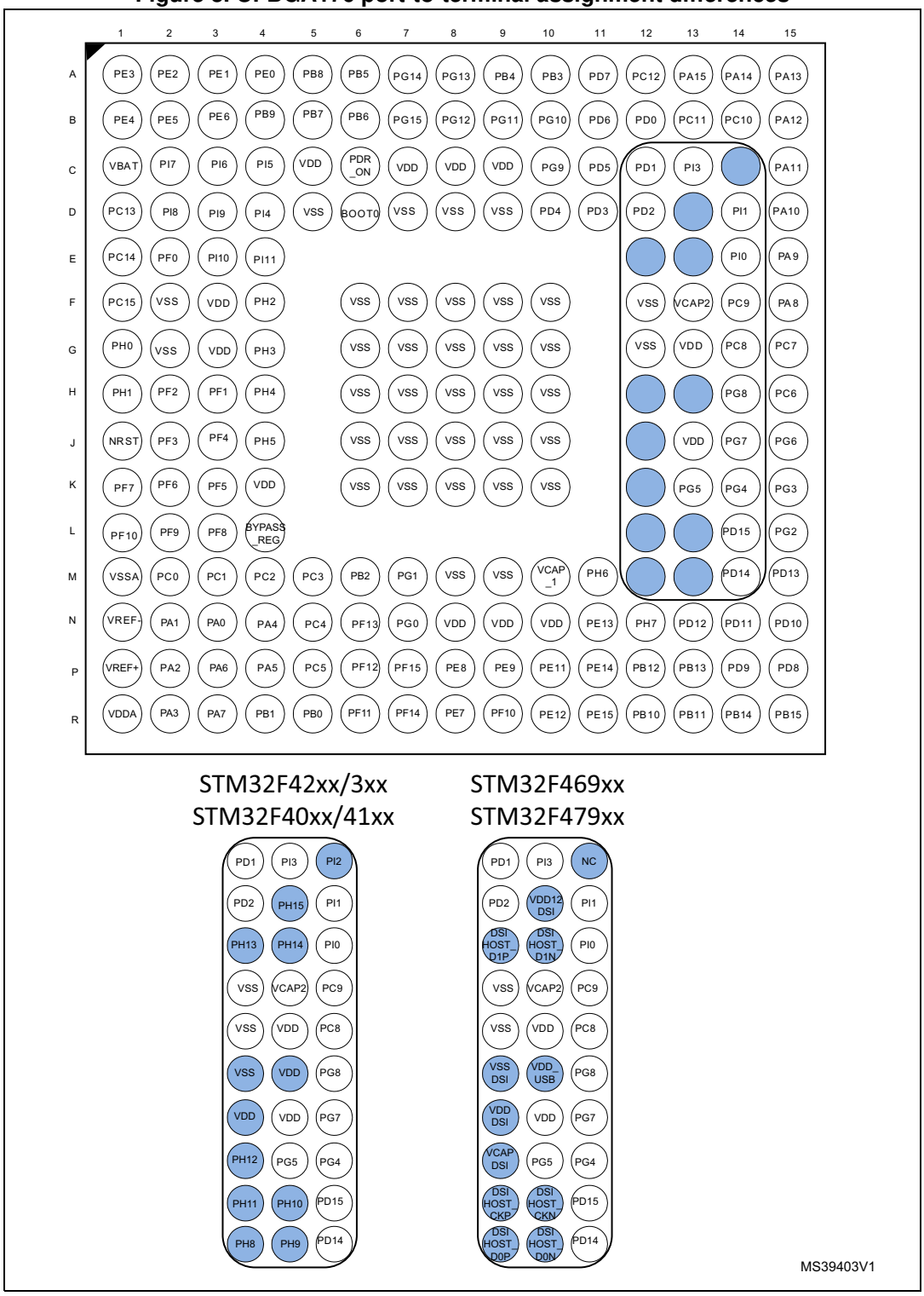
Figure 2. Incompatible board design for LQFP208 package



1. Pins from 118 to 128 and pin 137 are not compatible

1.1.3 UFBGA176 package

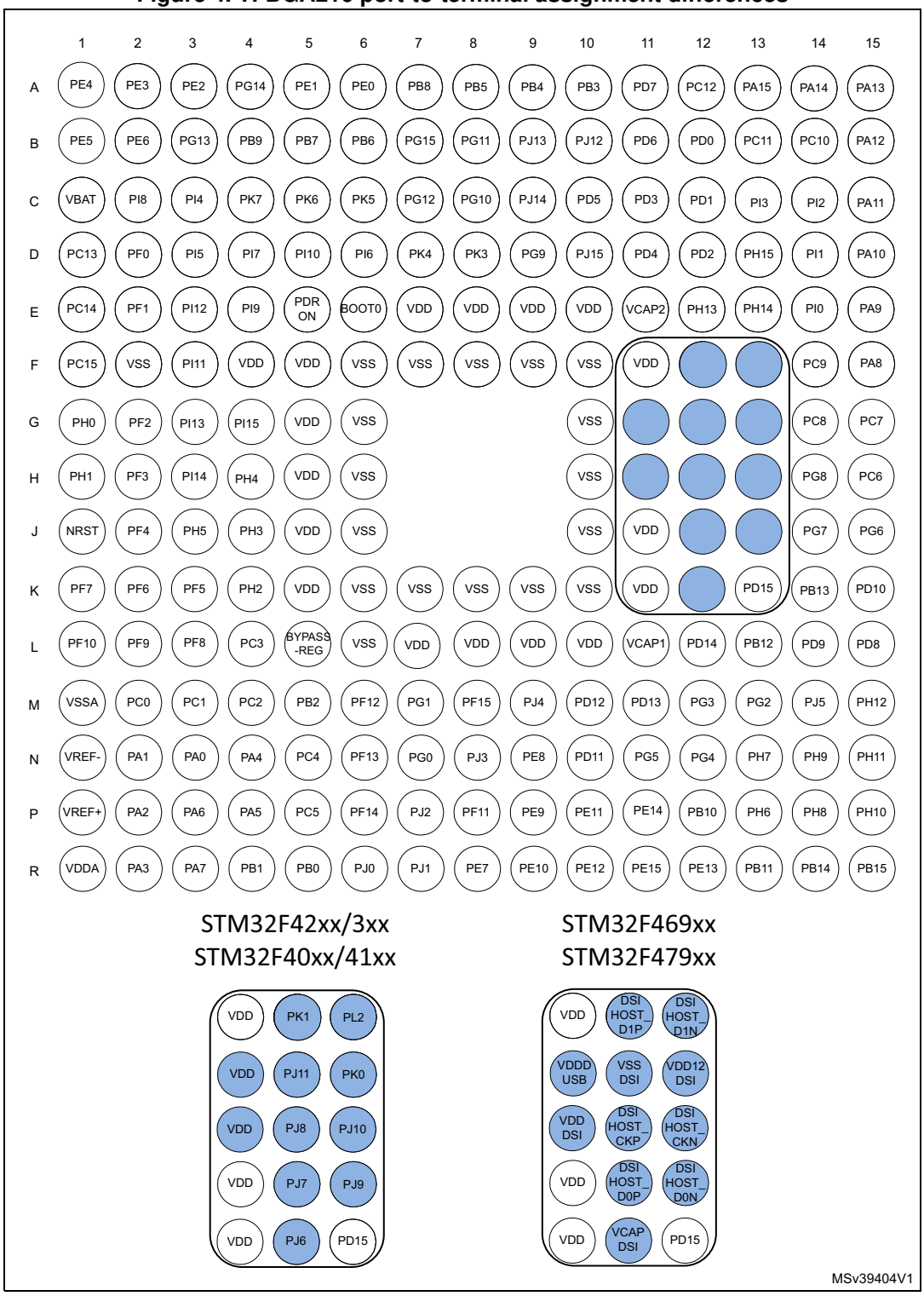
Figure 3. UFBGA176 port-to-terminal assignment differences



1. The highlighted pins are substituted with dedicated DSI IO pins on STM32F469xx/479xx devices.

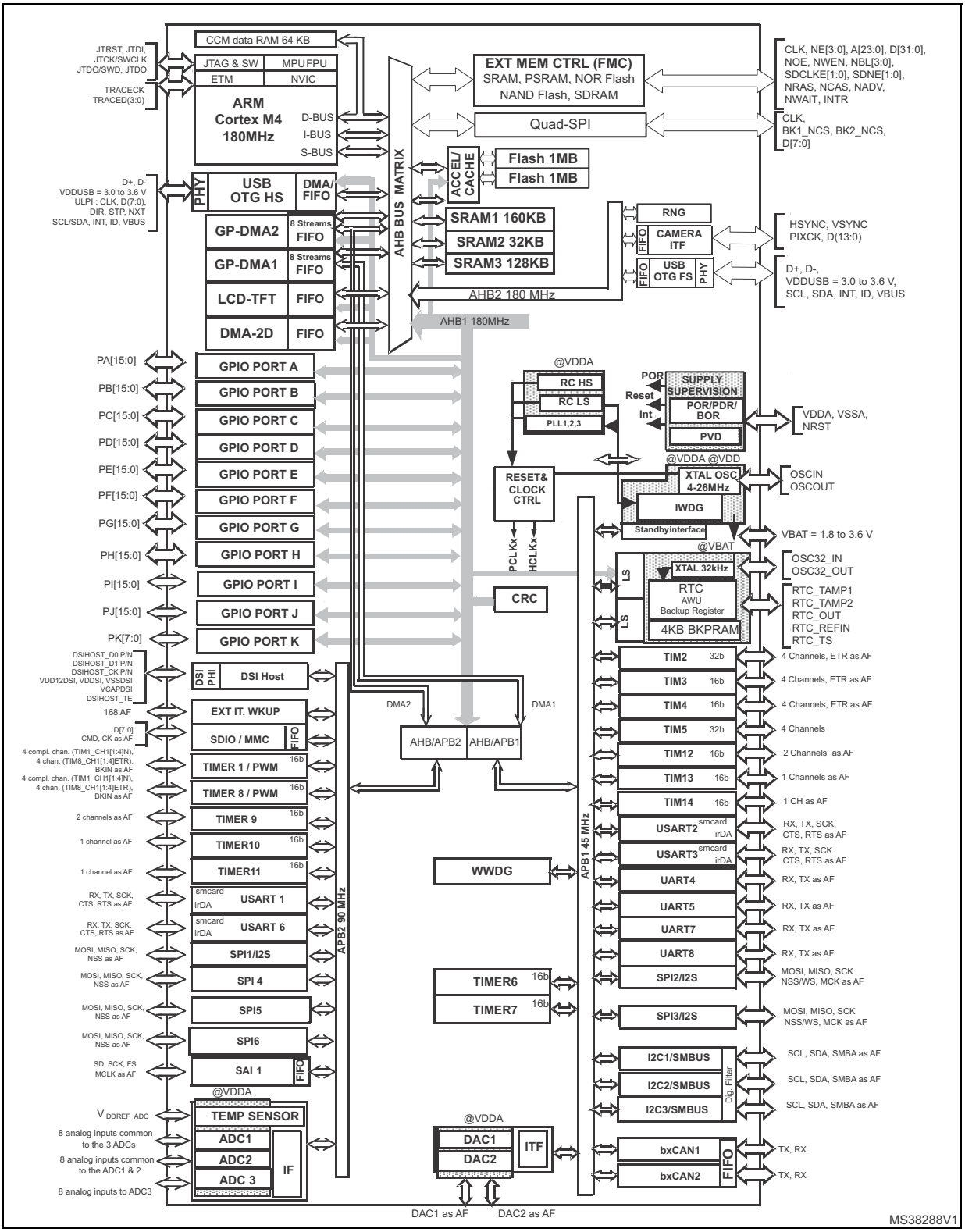
1.1.4 TFBGA216 package

Figure 4. TFBGA216 port-to-terminal assignment differences



1. The highlighted pins are substituted with dedicated DSI IO pins on STM32F469xx/479xx devices.

Figure 5. STM32F469xx block diagram



1. The timers connected to APB2 are clocked from TIMxCLK up to 180 MHz, while the timers connected to APB1 are clocked from TIMxCLK either up to 90 MHz or 180 MHz depending on TIMPRE bit configuration in the RCC_DCKCFGR register.

2 Functional overview

2.1 ARM® Cortex®-M4 with FPU and embedded Flash and SRAM

The ARM® Cortex®-M4 with FPU processor is the latest generation of ARM processors for embedded systems. It was developed to provide a low-cost platform that meets the needs of MCU implementation, with a reduced pin count and low-power consumption, while delivering outstanding computational performance and an advanced response to interrupts.

The ARM® Cortex®-M4 with FPU core is a 32-bit RISC processor that features exceptional code-efficiency, delivering the high-performance expected from an ARM core in the memory size usually associated with 8- and 16-bit devices.

The processor supports a set of DSP instructions which allow efficient signal processing and complex algorithm execution.

Its single precision FPU (floating point unit) speeds up software development by using metalanguage development tools, while avoiding saturation.

The STM32F46x line is compatible with all ARM tools and software.

Figure 5 shows the general block diagram of the STM32F46x line.

Note: Cortex®-M4 with FPU core is binary compatible with the Cortex®-M3 core.

2.2 Adaptive real-time memory accelerator (ART Accelerator™)

The ART Accelerator™ is a memory accelerator optimized for STM32 industry-standard ARM® Cortex®-M4 with FPU processors. It balances the inherent performance advantage of the ARM® Cortex®-M4 with FPU over Flash memory technologies, which normally require the processor to wait for the Flash memory at higher frequencies.

To release the processor full 225 DMIPS performance at this frequency, the accelerator implements an instruction prefetch queue and branch cache, which increases program execution speed from the 128-bit Flash memory. Based on CoreMark® benchmark, the performance achieved thanks to the ART Accelerator is equivalent to 0 wait state program execution from Flash memory at a CPU frequency up to 180 MHz.

2.3 Memory protection unit

The memory protection unit (MPU) is used to manage the CPU accesses to memory to prevent one task to accidentally corrupt the memory or resources used by any other active task. This memory area is organized into up to 8 protected areas that can in turn be divided up into 8 subareas. The protection area sizes are between 32 bytes and the whole 4 gigabytes of addressable memory.

The MPU is especially helpful for applications where some critical or certified code has to be protected against the misbehavior of other tasks. It is usually managed by an RTOS (real-time operating system). If a program accesses a memory location that is prohibited by the MPU, the RTOS can detect it and take action. In an RTOS environment, the kernel can dynamically update the MPU area setting, based on the process to be executed.

The MPU is optional and can be bypassed for applications that do not need it.

2.4 Embedded Flash memory

The devices embed a Flash memory of up to 2 Mbytes available for storing programs and data.

2.5 CRC (cyclic redundancy check) calculation unit

The CRC (cyclic redundancy check) calculation unit is used to get a CRC code from a 32-bit data word and a fixed generator polynomial.

Among other applications, CRC-based techniques are used to verify data transmission or storage integrity. In the scope of the EN/IEC 60335-1 standard, they offer a means of verifying the Flash memory integrity. The CRC calculation unit helps compute a software signature during runtime, to be compared with a reference signature generated at link-time and stored at a given memory location.

2.6 Embedded SRAM

All devices embed:

- Up to 384Kbytes of system SRAM including 64 Kbytes of CCM (core coupled memory) data RAM

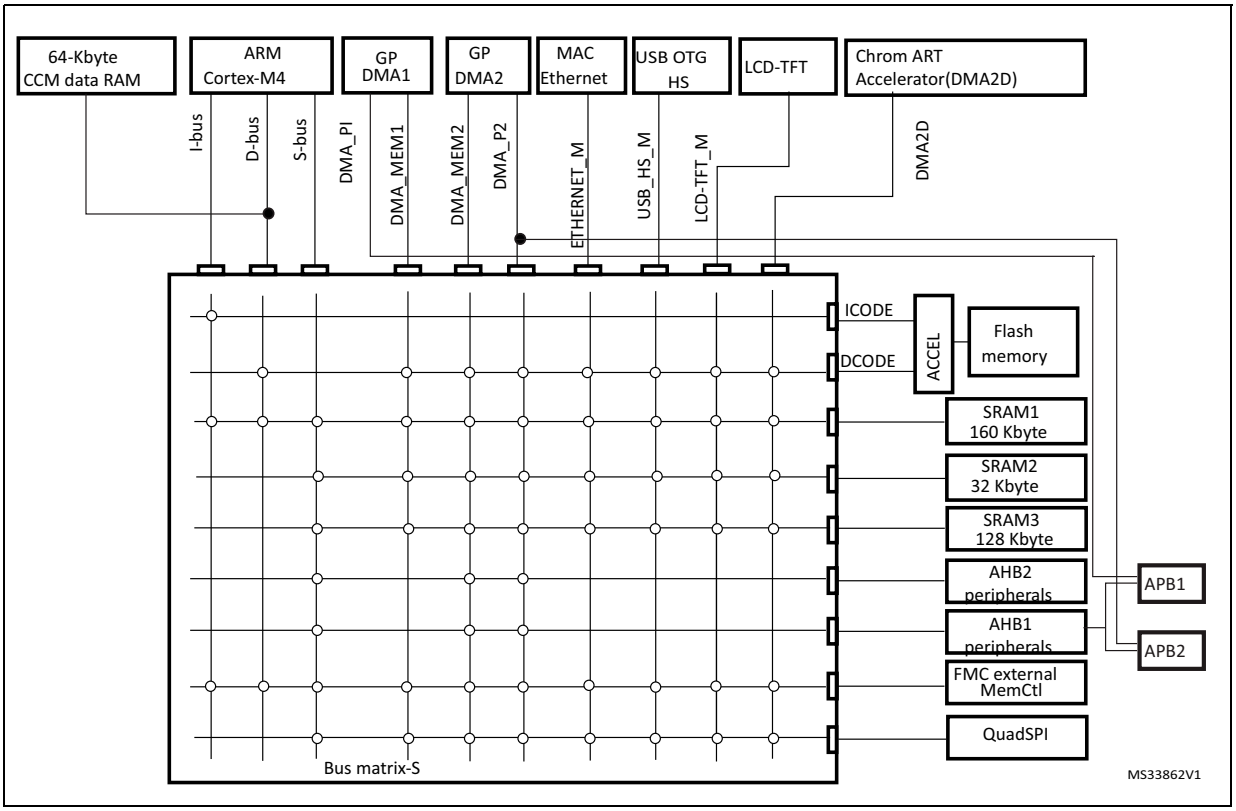
  RAM memory is accessed (read/write) at CPU clock speed with 0 wait states.
- 4 Kbytes of backup SRAM

  This area is accessible only from the CPU. Its content is protected against possible unwanted write accesses, and is retained in Standby or V_{BAT} mode.

2.7 Multi-AHB bus matrix

The 32-bit multi-AHB bus matrix interconnects all the masters (CPU, DMAs, Ethernet, USB HS, LCD-TFT, and DMA2D) and the slaves (Flash memory, RAM, FMC, QUADSPI, AHB and APB peripherals) and ensures a seamless and efficient operation even when several high-speed peripherals work simultaneously.

Figure 6. STM32F469xx Multi-AHB matrix



2.8 DMA controller (DMA)

The devices feature two general-purpose dual-port DMAs (DMA1 and DMA2) with 8 streams each. They are able to manage memory-to-memory, peripheral-to-memory and memory-to-peripheral transfers. They feature dedicated FIFOs for APB/AHB peripherals, support burst transfer and are designed to provide the maximum peripheral bandwidth (AHB/APB).

The two DMA controllers support circular buffer management, so that no specific code is needed when the controller reaches the end of the buffer. The two DMA controllers also have a double buffering feature, which automates the use and switching of two memory buffers without requiring any special code.

Each stream is connected to dedicated hardware DMA requests, with support for software trigger on each stream. Configuration is made by software and transfer sizes between source and destination are independent.

The DMA can be used with the main peripherals:

- SPI and I^2S
- I^2C
- USART
- General-purpose, basic and advanced-control timers TIMx
- DAC
- SDIO
- Camera interface (DCMI)
- ADC
- SAI1
- QUADSPI.

2.9 Flexible Memory Controller (FMC)

The Flexible memory controller (FMC) includes three memory controllers:

- The NOR/PSRAM memory controller
- The NAND/memory controller
- The Synchronous DRAM (SDRAM/Mobile LPSDR SDRAM) controller

The main features of the FMC controller are the following:

- Interface with static-memory mapped devices including:
  - Static random access memory (SRAM)
  - NOR Flash memory/OneNAND Flash memory
  - PSRAM
  - NAND Flash memory with ECC hardware to check up to 8 Kbytes of data
- Interface with synchronous DRAM (SDRAM/Mobile LPSDR SDRAM) memories
- 8-,16-,32-bit data bus width
- Independent Chip Select control for each memory bank
- Independent configuration for each memory bank
- Write FIFO
- Read FIFO for SDRAM controller
- The Maximum FMC_CLK/FMC_SDCLK frequency for synchronous accesses is HCLK/2.

LCD parallel interface

The FMC can be configured to interface seamlessly with most graphic LCD controllers. It supports the Intel 8080 and Motorola 6800 modes, and is flexible enough to adapt to specific LCD interfaces. This LCD parallel interface capability makes it easy to build cost effective graphic applications using LCD modules with embedded controllers or high performance solutions using external controllers with dedicated acceleration.

2.10 Quad-SPI memory interface (QUADSPI)

All STM32F469xx devices embeds a Quad-SPI memory interface, which is a specialized communication interface targeting Single, Dual, Quad or Dual-flash SPI memories. It can work in direct mode through registers, external flash status register polling mode and memory mapped mode. Up to 256 Mbytes external Flash memory are mapped, supporting 8, 16 and 32-bit access. Code execution is supported.

The opcode and the frame format are fully programmable. Communication can be either in Single Data Rate or Dual Data Rate.

2.11 LCD-TFT controller

The LCD-TFT display controller provides a 24-bit parallel digital RGB (Red, Green, Blue) and delivers all signals to interface directly to a broad range of LCD and TFT panels up to XGA (1024x768) resolution with the following features:

- 2 displays layers with dedicated FIFO (64x32-bit)
- Color Look-Up table (CLUT) up to 256 colors (256x24-bit) per layer
- Up to 8 Input color formats selectable per layer
- Flexible blending between two layers using alpha value (per pixel or constant)
- Flexible programmable parameters for each layer
- Color keying (transparency color)
- Up to 4 programmable interrupt events.

2.12 DSI Host (DSIHOST)

The DSI Host is a dedicated peripheral for interfacing with MIPI® DSI compliant displays. It includes a dedicated video interface internally connected to the LTDC and a generic APB interface that can be used to transmit information to the display.

These interfaces are as follows:

- LTDC interface:
  - Used to transmit information in Video Mode, in which the transfers from the host processor to the peripheral take the form of a real-time pixel stream (DPI).
  - Through a customized for mode, this interface can be used to transmit information in full bandwidth in the Adapted Command Mode (DBI).
- APB slave interface:
  - Allows the transmission of generic information in Command mode, and follows a proprietary register interface.
  - Can operate concurrently with either LTDC interface in either Video Mode or Adapted Command Mode.
- Video mode pattern generator:
  - Allows the transmission of horizontal/vertical color bar and D-PHY BER testing pattern without any kind of stimuli.